

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC035N10NS5	**Issued**	4. March 2019
MA#	MA001626148		
Package	PG-TDSON-8-7	**Weight***	119.71 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.818	1.52	1.52	15190	15190
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	iron	7439-89-6	0.038	0.03		316	
	non noble metal	copper	7440-50-8	37.762	31.54	31.58	315440	315851
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	372	372
encapsulation	organic material	carbon black	1333-86-4	0.085	0.07		706	
	plastics	epoxy resin	-	6.679	5.58		55794	
	inorganic material	silicondioxide	60676-86-0	35.509	29.66	35.31	296625	353125
leadfinish	non noble metal	tin	7440-31-5	1.452	1.21	1.21	12126	12126
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1383	1383
solder	non noble metal	tin	7440-31-5	0.050	0.04		416	
	noble metal	silver	7440-22-4	0.062	0.05		520	
	non noble metal	lead	7439-92-1	2.380	1.99	2.08	19879	20815
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	iron	7439-89-6	0.011	0.01		95	
	non noble metal	copper	7440-50-8	11.320	9.46	9.47	94561	94684
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	iron	7439-89-6	0.022	0.02		186	
	non noble metal	copper	7440-50-8	22.292	18.62	18.65	186212	186454
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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